

HRG300

High Rigid Grinder

High Rigid Grinding

Fast and Damageless

Low Cost

Batch Processing Available

In-process Dressing (optional)





Target Material

Hard Brittle Material as Sapphire, SiC, GaN, and AlN

Target Work

Size : $\phi 2$ to $\phi 12$ inch

Maximum Thickness : 20mm (include base plate)

Actual Result Example

Materials	Size	Numbers processed	Grinded thickness	Processing time
Sapphire	$\phi 4$ inch	4 wafers/batch	530 μm	10mins(2min30sec/each)
SiC	$\phi 4$ inch	Single Processing	120 μm	1 min
AlN	$\phi 6$ inch	Single Processing	500 μm	4 mins

Specification



No	Category	ACCURETECH
		High-Rigid Grinder
1	Appearance (mm)	Size : 1540(W) x 1880(D) x 2010(H) Weight : 3850 kg
2	Max Processing Diameter (mm)	300
3	Grinding Wheel Diameter (mm)	300
4	Grinding Wheel Rotation (rpm)	3600
5	Work Spindle Rotation (rpm)	400
6	Grinding Wheel Spindle (Kw)	11
7	Work Spindle (Kw)	2
8	Automatic Monitor	In-process gauge (Batch process available)
9	Infeed Control Resolution (μm)	0.01
10	In-process Dressing	option

ACCURETECH

Japan / Head Office Tokyo Seimitsu Co., Ltd.
2968-2, Ishikawa-machi, Hachioji-shi, Tokyo, 192-8515 Japan
TEL : (042) 642-1701 FAX : (042) 642-1798
<https://www.accuretech.com/en/>

Contact
information

